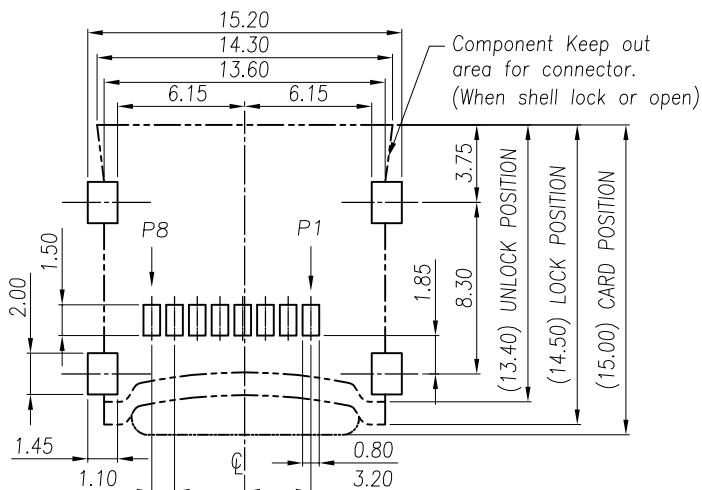
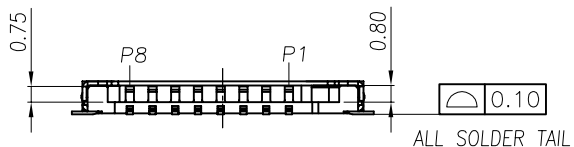
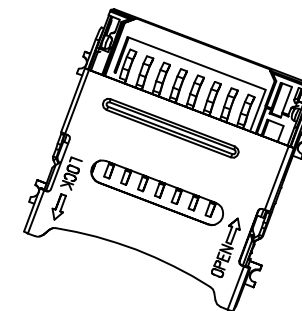
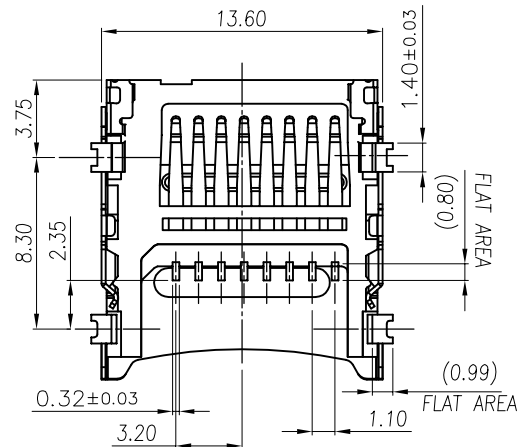
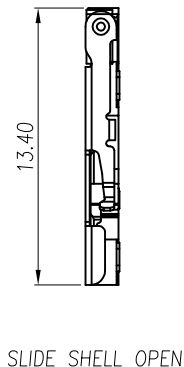
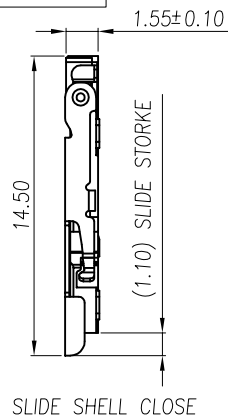
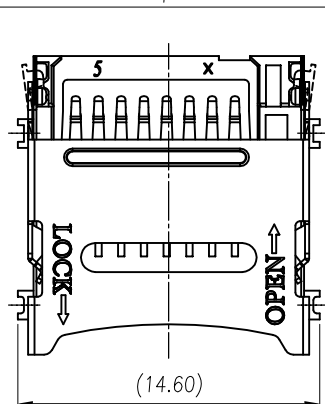


The product using material and processing must conform to the "WI-PZ-001"HSF technical standard control requirements

RoHS



RECOMMENDED PCB LAYOUT(TOP VIEW)
GENERAL TOLERANCES:±0.05

Pin No.	NAME	TYPE	DESCRIPTION
1	DAT 2	I/O/PP	Date Line(bit2)
2	CD/DAT 3	I/O/PP	Card Detect/Date Line(bit3)
3	CMD	PP	Command Response
4	VDD	S	Supply Voltage
5	CLK	I	Colck
6	VSS	S	Supply Voltage Ground
7	DAT0	I/O/PP	Date Line(bit0)
8	DAT1	I/O/PP	Date Line(bit1)

NOTE:
1.MATERIAL SPECIFICATION:
1-1.HOUSING:LCP UL94 V-0
1-2.CONTACTS:COPPER ALLOY.
1-3.SHIELDED:SUS201
2.PLATING SPECIFICATION:
2-1.CONTACTS: SELECTIVE GOLD PLATED ON CONTACT AREA
100u" Min. TIN PLATED ON SOLDER TAIL
50u" Min. NICKEL UNDER-PLATED
2-2. SHELL:
NO PLATED
3.ELECTRICAL PERFORMANCE:
3-1.CURRENT RATING:0.5A
3-2.VOLTAGE RATING:12V MAX
3-3.CONTACT RESISTANCE: 50m Ohm MAX.
3-4.INSULATION RESISTANCE: 100MQ MIN 100V DC
3-5.DIELECTRIC WITHSTANDING VOLTAGE: 100V AC MIN.
4.ENVIRONMENTAL PERFORMANCE:
OPERATING TEMPERATURE: -20°C~+85°C.

WLTF9-08 2 X X 0 003
PLATING: 1-G/F
2-AU 3U"
5-AU 15U"
6-AU 30U"
COLOUR:
A:Black

REV.	REVISION RECORD	DATE	UNIT:mm	GENERAL TOLERANCES		SCALE:	NAME	DATE	PART.NO:	DWG.NO:	TITLE:	REV: A0	SHEET: 1/1
AO	NEW RELEASE	21.01.13		LINEAR	ANGLES	1:1							
				0.00±0.25	X'±3'	APPROVED	Wang_jr	21.01.13	WLTF9-082XX0003	ENDE05			
			SIZE: A4	0.000±0.10	X'X' ±2'	DESIGNER	Ding_bo	21.01.13					
						DRAWN	Ou_jian	21.01.13					



REV: A0 SHEET: 1/1